

**INSTRUCTIONS TO PREPARE A ONE PAGE ABSTRACT FOR  
THE Eighth INTERNATIONAL CONFERENCE ON SMART MATERIALS AND  
NANOTECHNOLOGY IN ENGINEERING (SMN2024)**

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**ABSTRACT**

Authors interested in submitting a contribution to SMN 2024 are requested to submit electronically a one-page abstract not later than **June 28, 2024**. Abstracts should briefly outline the main features, results and conclusions as well as their general significance, and contain relevant references.

Full details of the content of the contribution can be included in the paper (6 to 10 pages). The submission of the full paper is optional.

The abstract should be written following the format of the template for submission that can be found at the conference website. They must be converted to Portable Document Format (PDF) before submission through the conference site.

The abstract has to be written in English with Times-Roman letters, size 10.

The abstract must contain the full name/s and affiliation/s of author/s. In the case of joint authorship, the name of the author who will actually present the paper at the conference should be underlined. Submissions can only be accepted on the understanding that they will be presented at the conference by a registered author.

For any inquiries, please contact us via email at smn2024@aus.edu

**References**

- [1] E. Oñate and M. Cervera, Derivation of thin plate bending elements with one degree of freedom per node, *Engng. Comput.*, Vol. 10, pp. 543–561, 1993.
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